

• General Description

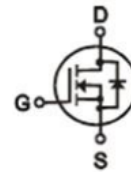
The ZM040N06B combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- SMPS 2nd Synchronous Rectifier
- BLDC Motor driver

• Product Summary

 $V_{DS}=60V$
 $R_{DS(ON)}=3.8m\Omega$
 $I_D=120A$

TO-263
• Ordering Information:

Part NO.	ZM040N06B
Marking	ZM040N06
Packing Information	Bulk Tube
Basic ordering unit (pcs)	500

• Absolute Maximum Ratings (T_c =25°C)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	$I_{D@TC=25^{\circ}C}$	120	A
	$I_{D@TC=75^{\circ}C}$	91.2	A
	$I_{D@TC=100^{\circ}C}$	75.6	A
Pulsed Drain Current ①	I_{DM}	250	A
Total Power Dissipation(TC=25°C)	$P_D@TC=25^{\circ}C$	120	W
Total Power Dissipation(TA=25°C)	$P_D@TA=25^{\circ}C$	5	W
Operating Junction Temperature	T_J	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1	$^{\circ}C/W$
Thermal resistance, junction - ambient	R_{thJA}	-	-	25	$^{\circ}C/W$
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	$^{\circ}C$

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.3		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$		3.8	5.0	$m\Omega$
	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 16A$		4.6	6.0	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = 25V, I_D = 15A$		32		s
Source-drain voltage	V_{SD}	$I_S = 20A$			1.28	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$f = 1MHz$	-	6510	-	pF
Output capacitance	C_{oss}		-	450	-	
Reverse transfer capacitance	C_{rss}		-	200	-	

•Gate Charge characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	$V_{DD} = 25V$	-	54	-	nC
Gate - Source charge	Q_{gs}	$I_D = 25A$	-	18	-	
Gate - Drain charge	Q_{gd}	$V_{GS} = 10V$	-	21	-	

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;

Fig.1 Gate-Charge Characteristics

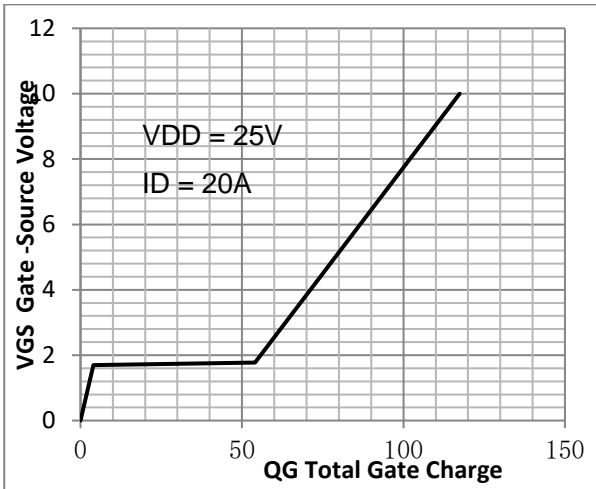


Fig.2 Capacitance Characteristics

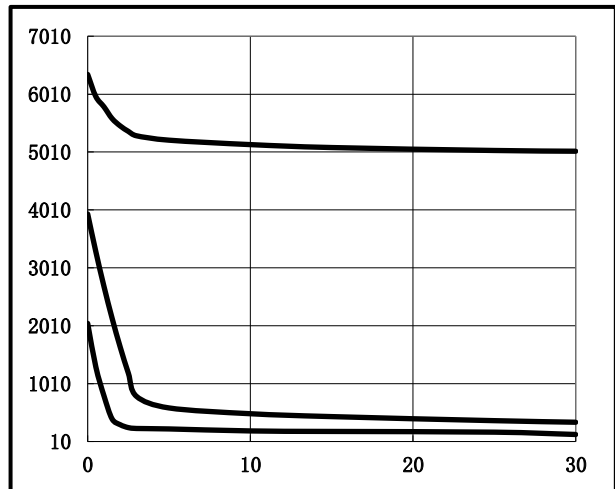


Fig.3 Power Dissipation

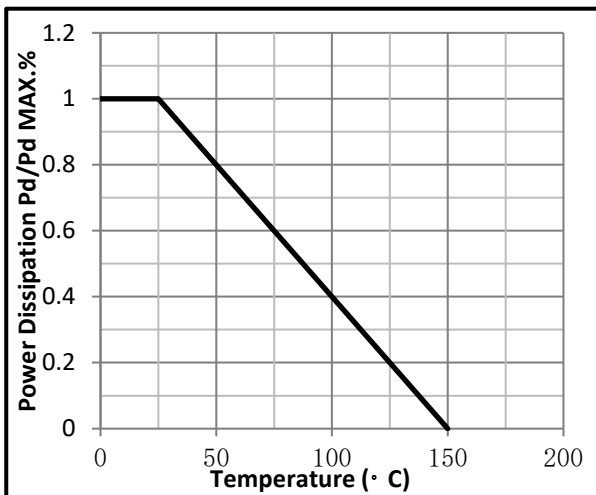


Fig.4 Typical output Characteristics

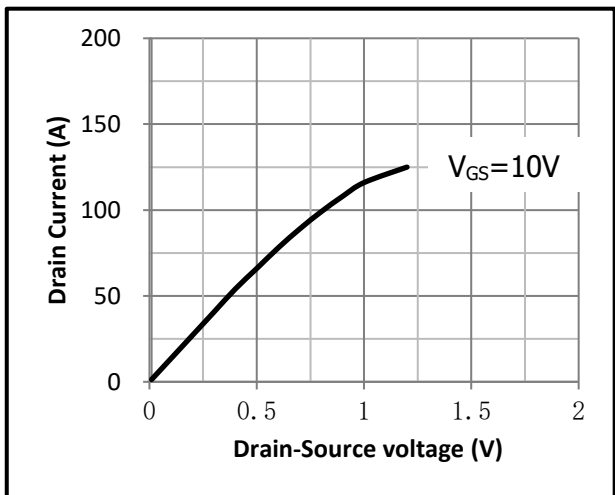


Fig.5 Threshold Voltage V.S Junction Temperature

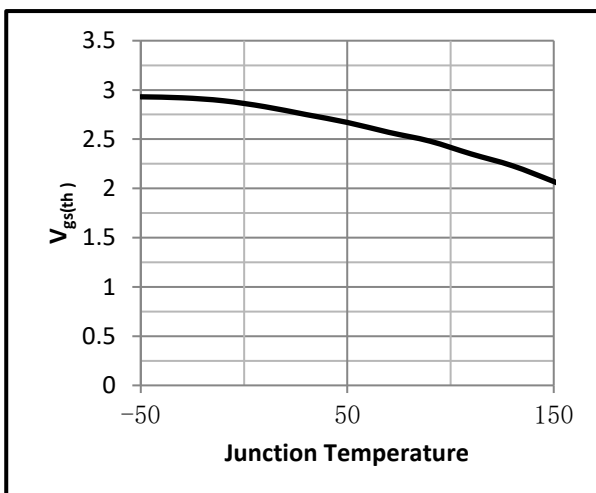


Fig.6 Resistance V.S Drain Current

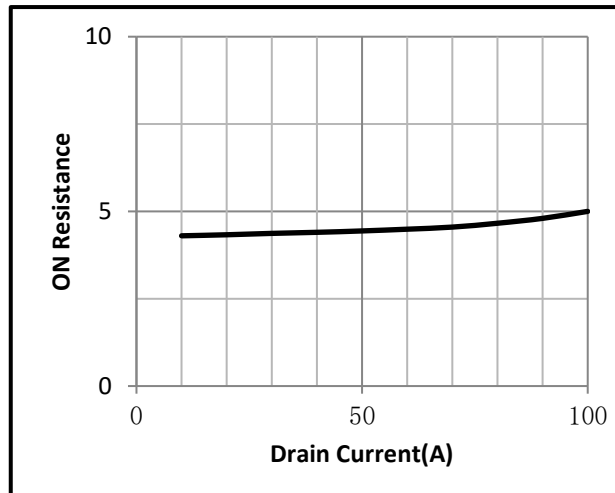


Fig.7 On-Resistance VS Gate Source Voltage

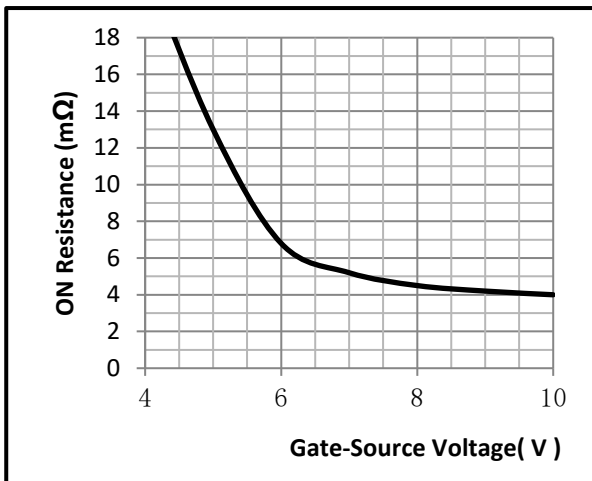


Fig.8 On-Resistance V.S Junction Temperature

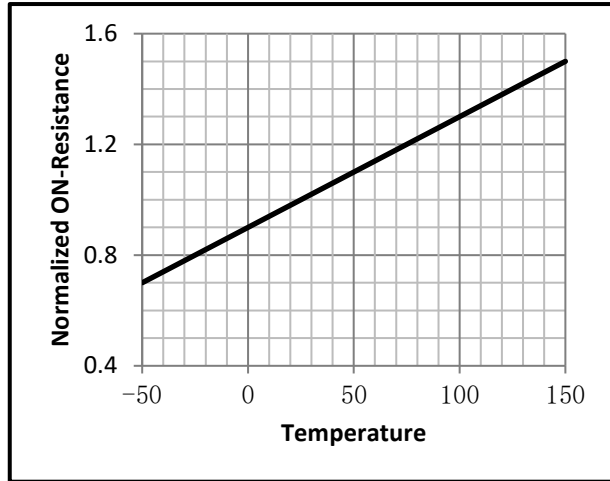


Fig.9 Switching Time Measurement Circuit

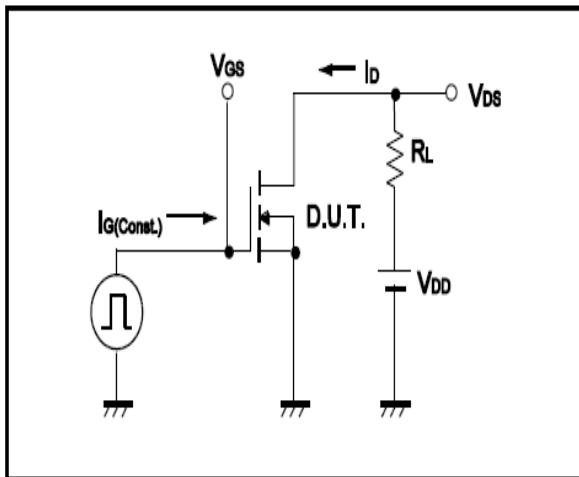


Fig.10 Gate Charge Waveform

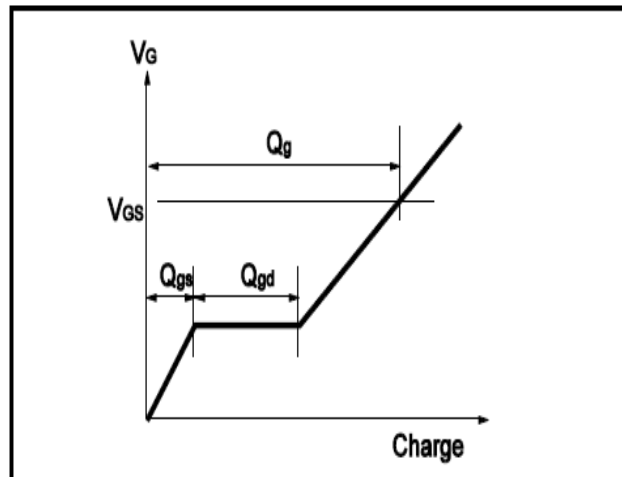


Fig.11 Switching Time Measurement Circuit

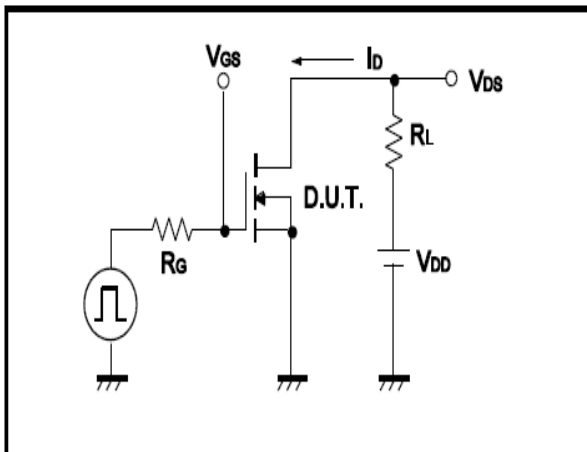
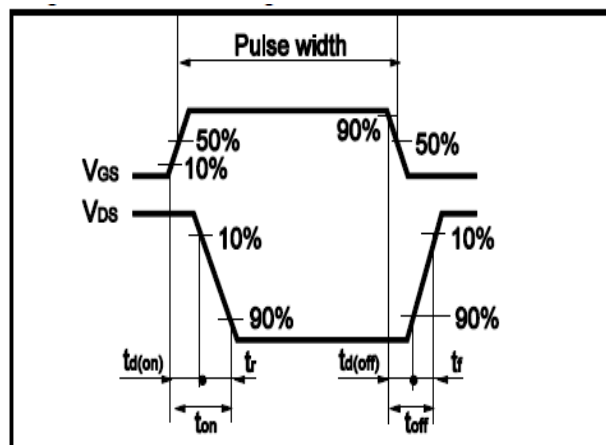


Fig.12 Gate Charge Waveform



• Dimensions (TO-263)

Unit: mm

SYMBOL	MIN	TYP	MAX	SYMBOL	MIN	TYP	MAX
A	4.42		4.72	E	8.99		9.29
B	1.22		1.32	e1	2.44		2.64
b	0.76		0.86	e2	4.98		5.18
b1	1.22		1.32	L1	15.19		15.79
b2	0.33		0.43	L2	2.29		2.79
C	1.22		1.32	L3	1.3		1.75
D	9.95		10.25				

